

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	dummy wafer coating entire wubstrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 11:23
L2	0	dummy wafer and coating entire wubstrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 11:23
L3	0	monitor wafer and coating entire wubstrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 11:23
L4	104	monitor wafer and coating entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 11:23
L5	9	monitor wafer coating entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 11:23
L6	0	monitor wafer and coat\$4 entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	NEAR	ON	2008/08/28 11:26
L7	50	monitor wafer and coat\$4 entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 11:26
L8	1	("2002/0072249").URPN.	USPAT	OR	OFF	2008/08/28 11:31
L12	0	("2002/0151428").URPN.	USPAT	OR	OFF	2008/08/28 11:56
L13	5	("6051096" "6258737" "6576076").PN. OR ("6841273").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/28 11:56
L14	53	"5904778"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/28 12:03
L15	37	polish\$3 ((silicon adj carbide) or sic) (film or coat\$4) surface roughness	US-PGPUB; USPAT; USOCR	WITH	ON	2008/08/28 12:27
L16	48	dummy wafer and coating entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 12:44
L17	1	("20020053321").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/28 12:57
L18	1	("5939130").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/28 13:01
L19	79	dummy wafer and coat\$4 entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 13:05

L20	31	19 not 16	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 13:05
L21	130	dummy wafer and coat\$4 side substrate	US-PGPUB; USPAT; USOCR; DERWENT	SAME	ON	2008/08/28 13:06
L22	1	("5937316").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/28 15:18
L23	4	monitor wafer and film entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	NEAR	ON	2008/08/28 16:09
L24	100	monitor wafer and film entire substrate	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 16:10
L25	2	(monitor wafer).ab. and ((coat\$4 or layer or film) entire substrate)	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 16:11
L26	14	(dummy wafer).ab. and ((coat\$4 or layer or film) entire substrate)	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 16:11
L27	65	(dummy near wafer) and ((coat\$4 or layer or film) entire substrate)	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 16:12
L28	2	(dummy near wafer).ti. and ((coat\$4 or layer or film) (whole or entire or side) substrate)	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/28 16:24
S1	270	(dummy or monitor or nonproduction) ((silicon with carbide) or sic) wafer	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:00
S2	81778	(coat\$4 or layer\$4) ((silicon with carbide) or sic)	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:01
S3	197	S1 and "2"	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:02
S4	155	S1 and S2	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:02
S5	190	(dummy or monitor or nonproduction) ((silicon with carbide) or sic) substrate	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:10
S6	3642	(dummy or monitor or nonproduction) and ((silicon with carbide) or sic) substrate	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:10

S7	583	((dummy or monitor or nonproduction) (wafer)) and ((silicon with carbide) or sic) substrate	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:10
S8	396	S2 and S7	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 15:11
S9	832	sinter\$4 ((silicon with carbide) or sic) substrate	US-PGPUB; USPAT; USOCR; JPO; DERWENT	WITH	ON	2008/08/27 15:30
S10	520	S2 and S9	US-PGPUB; USPAT; USOCR; JPO; DERWENT	WITH	ON	2008/08/27 15:30
S11	1160	(427/249.15,249.16,585,589).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/27 15:35
S12	12	S9 and S11	US-PGPUB; USPAT; USOCR; DERWENT	OR	OFF	2008/08/27 15:35
S13	3941846	(silicon carbide or sic) powder non-metallic sintering (aid or auxiliary)	US-PGPUB; USPAT; USOCR; DERWENT	OR	OFF	2008/08/27 15:41
S14	27	(silicon carbide or sic) powder non-metallic sintering (aid or auxiliary)	US-PGPUB; USPAT; USOCR; DERWENT	WITH	ON	2008/08/27 15:41
S15	1	("7087980").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/27 16:05
S16	49	(dummy or monitor or nonproduction) ((silicon with carbide) or sic) wafer coat\$4	US-PGPUB; USPAT; USOCR; JPO; DERWENT	SAME	ON	2008/08/27 16:21
S17	312	(427/249.15).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/27 16:34
S18	89	S17 and ((silicon with carbide) or sic) adj3 (substrate or base)	US-PGPUB; USPAT; USOCR; DERWENT	OR	OFF	2008/08/27 16:35
S19	13	S17 and ((silicon with carbide) or sic) adj (substrate or base)	US-PGPUB; USPAT; USOCR; DERWENT	OR	OFF	2008/08/27 16:35
S20	0	(2002/0173125).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/27 16:45
S21	1	("20020173125").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/08/27 16:45

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